

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Previously presented) An optoelectronic component based on a surface mount technology, the optoelectronic component comprising:
  - an electrically conductive frame forming a base for an assembly;
  - an opaque plastic material forming a housing for the assembly;
  - a cavity formed within the plastic material;
  - at least one protrusion extending from a side surface of the housing to provide heat dissipation; and
  - at least one optoelectronic chip mounted in the cavity,
    - wherein the base emanates from an internal middle portion and protrudes from a bottom surface and two other side surfaces of the housing, the bottom surface and the two other side surfaces of the housing providing external mounting connection terminals.
2. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the cavity is filled with a transparent or translucent resin material.
3. (Previously presented) The optoelectronic component as claimed in claim 1, wherein an electrical connection between the at least one optoelectronic chip and the base is provided by a metallic wire.

4. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the external mounting connection terminals are provided for connecting to external sub-systems.

5. (Canceled)

6. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the base protrudes outside the plastic material.

7-8. (Canceled)

9. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the external mounting connection terminals are provided without any lead formations.

10. (Previously presented) An optoelectronic component based on a surface mount technology, the optoelectronic component comprising:

an electrically conductive frame forming a base for an assembly;

an opaque plastic material forming a housing for the assembly;

a cavity formed within the plastic material;

at least one protrusion extending from a side surface of the housing to provide heat dissipation; and

at least one optoelectronic chip mounted in the cavity,  
wherein the electrically conductive frame emanates from an internal middle  
portion and protrudes to two other side surfaces of the housing, the two other side  
surfaces of the housing providing external mounting connection terminals.

11. (Previously presented) The optoelectronic component as claimed in claim  
10, wherein the cavity is filled with a transparent or translucent resin material.

12. (Previously presented) The optoelectronic component as claimed in claim  
10, wherein the external mounting connection terminals are provided without any lead  
formations.

13. (Previously presented) The optoelectronic component as claimed in claim  
10, wherein an electrical connection between the at least one optoelectronic chip and  
the base is provided by a metallic wire.

14. (Previously presented) The optoelectronic component as claimed in claim  
10, wherein the external mounting connection terminals are provided for connecting to  
external sub-systems such as PCBs.

15. (Previously presented) The optoelectronic component as claimed in claim 1,  
wherein the at least one protrusion extending from a side surface to provide heat

dissipation extends further from the side surface than the base protrusion on the bottom surface extends from the bottom surface.

16. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the base protrusion on the bottom surface extends along the bottom surface for at least a third of a length of the bottom surface.

17. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the base comprises two separate base sections, each of the base sections protruding from the bottom surface and at least one of the two other side surfaces.

18. (Previously presented) The optoelectronic component as claimed in claim 17, wherein one of the two base sections is larger than the other in the middle portion and the protrusions of the two base sections have identical dimensions outside the housing.

19. (Previously presented) The optoelectronic component as claimed in claim 18, wherein the optoelectronic chip is arranged on the larger one of the two base sections.

20. (Previously presented) The optoelectronic component as claimed in claim 10, wherein the electrically conductive frame comprises two separate frames, each of the frames protruding from at least one of the two other side surfaces.

21. (Previously presented) The optoelectronic component as claimed in claim 20, wherein one of the two frames is larger than the other in the middle portion.

22. (Previously presented) The optoelectronic component as claimed in claim 21, wherein the protrusions of the two frames have identical dimensions outside the housing.

23. (Previously presented) The optoelectronic component as claimed in claim 21, wherein the optoelectronic chip is arranged on the larger one of the frames.

24. (New) The optoelectronic component as claimed in claim 1, wherein the base protrudes from the bottom surface and the two other side surfaces of the housing so as to extend past the bottom surface and the two other side surfaces of the housing.

25. (New) The optoelectronic component as claimed in claim 10, wherein the electrically conductive frame protrudes to the two other side surfaces of the housing so as to extend past the two other side surfaces of the housing.